Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model
[List multiple models if applicable.]

HP HC240 Healthcare 24-inch Display

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Function key BD, IF BD, POWER BD</td>
<td>3</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Power BD only (C805)</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>USB cable, Mini Display cable, Display cable, Power cord</td>
<td>4</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#0</td>
</tr>
<tr>
<td>Description #2 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#1</td>
</tr>
<tr>
<td>Description #3 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#2</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Stand Base From Display Head
2. Remove Rear Cover From Display Head
3. Remove Bracket Assy From Display Head
4. Remove Mid cover From Display Head
5. Remove Front Cover From Display Head
6. Disassemble Front Cover
7. Disassemble Bracket ASSY
8. Disassemble Stand ASSY
9. Disassemble Panel ASSY
10.  
11.  

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
HP HC240 Disassembly Process

- Steve Chou
- Mechanical Engineer
- August-18-2016
1. Remove Cable From Display Head.
3. Pull the release button

4. Remove Stand Base From Display Head.
5. Remove four wall mount screws from display head.

6. Remove Rear Cover From Display Head.
Remove Bracket from Display Head

7. Remove AL, tape, internal cable

8. Remove screw
Remove Mid-cover from head

9. Remove screw
Remove front cover from head
Disassemble front cover

11. Remove function key and Mylar
Disassemble Bracket ASSY

Remove Mylar

Remove Mylar, thermal pad and gasket

Remove Screws
Disassemble Stand ASSY

1. Remove screws
2. Remove pivot cover and Tilt 1 cover
3. Remove screw and tilt cover
4. Remove lift cover
Disassemble Stand ASSY

1. Remove rubber
2. Remove screw
3. Remove screw
4. Remove screw
Disassemble Stand ASSY

Remove screw

Remove VESA cover, slider, Spring and release button
Disassemble Panel ASSY

1. Loosen C/Shield Screw(*3), Dismantle C/Shield

2. Dismantle C/Top

3. Separate C/Top (push the C/Top because of damages on COF)

4. Separate B/Ass’y
Disassemble Panel ASSY

5. Loosen B/L Screw (*5)

6. Dismantle G/Panel

7. Removeal Optical sheets

8. Removeal LGP
Disassemble Panel ASSY

9. Removal Reflector

10. Separate LED Array from C/Bottom Assy

11. LED Array

Dissecting to complete.